ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® Material Comp © Copyright 2005. 1 international and Pa	PC. Bannock	burn, Illinois, A	Il rights reserved nations.	under both	This docume level parts, t	ent is a declaration en declaration	on of the su acompasses	bstances v s all lower	vithin the manufactu level materials for w	rer listed i which the n	tem. Note: if nanufacturer	the item is an as has engineering	ssembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175xFormation Distribution				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infe				fg Informati	on				
Supplier Information														
Company name*	Company un	Company unique ID			Unique ID Authority				Respon	Response Date*				
nsemi										2024-05	2024-05-15			
Contact Name Title - Contact			tact			Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewards Product En			et Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Repr			presentative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards Produ			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date Version Manufac		Ianufacturing Site	Weight*		UOM	Unit Type		
	NCV573 G	NCV57302DSADJR4 3A ADJ V G		ADJ VLDO REGULATOR		2024-05-15		М	MY1		1617.9136	mg	Each	
Manufacturing Proccess Informa	tion													
Terminal Plating / Grid Array M	aterial	Ferminal Base A	Alloy	y J-STD-020 MSL Rati		Peak Proce	Process Body Temperature Ma		e Max Time at Peak	Temperature Number of Reflow Cycles		cles		
Matte Tin (Sn) - annealed	Matte Tin (Sn) - annealed CU Alloy			1		260		С	30	secon	nds 3			
omments														
vel 1 - maximum time at peak temperat	ure during so	dering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).								
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature	astislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.19	mg	Supplier	Silicon (Si)	7440-21-3		0.19	mg
Die Attach	11.31	mg	А	Lead (Pb)	7439-92-1	7a	10.7445	mg
			Supplier	Tin (Sn)	7440-31-5		0.5655	mg
Lead Frame	843.0	mg	В	Nickel (Ni)	7440-02-0		2.529	mg
			Supplier	Copper (Cu)	7440-50-8		840.471	mg
Lead Frame plating	8.27	mg	Supplier	Silver (Ag)	7440-22-4		8.27	mg
Mold Compound-Black	727.2536	mg		Epoxy resin	proprietary data		36.3627	mg
				Phenolic Resin	Proprietary Data		36.3627	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		14.5451	mg
			Supplier	Carbon Black (C)	1333-86-4		3.6363	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		636.3469	mg
Plating	27.15	mg	Supplier	Tin (Sn)	7440-31-5		27.15	mg
Wire Bond - Cu	0.74	mg	Supplier	Copper (Cu)	7440-50-8		0.74	mg